

PCB Settings

Parámetros

Alto (H)	156	mm
Ancho (L)	120	mm
Grosor	1,60	mm
Nº Capas	4	--
Material	FR-4 tg170	--
Vias	Tenting Vias	--
Surface finish	Immersion Gold	--
Immersion Gold Thickness	1,00	mils
Drill Size	<= 0,25	mm

Distribución del stack, impedancia y tolerancias.

	Layer Name	Usage	Copper Weight (oz)	Copper Thickness (mils)	Dielectric Thickness (mils)	Single/Diff pair (ohm)	Tolerance	Single Width (mils)	Diff (90) width / Space(mil)	Diff (100) width / Space(mil)
		Solder Mask		1						
1	TOP	Signal	1	1.35		50/90/100	+/- 10%	6	8/5	8/7.5
		Substrate			7					
2	GND	Plane	1	1.35						
		Substrate			42					
3	PWR	Plane	1	1.35						
		Substrate			7					
4	BOTTOM	Signal	1	1.35		50/90/100	+/- 10%	6	8/5	8/7.5
		Solder Mask		1						

